Recommended Conditions of Moisture Sensitivity Level〔R06S00J00〕

■ Recommended Conditions for each symbol

R06	Floor life≦6days in a manufacturing environment 30℃/70%RH or less, A maximum of 2 reflow passes with FJ STD temp profile is allowed.
S00	Solder dip is impossible.
J00	It does not correspond to IPC/JEDEC J-STD-020A

If the specified floor life or ambient temperature/humidity conditions shown above have been exceeded devices must be baked for 24hours at 125℃(Maximum 2 cycles of baking are allowed).

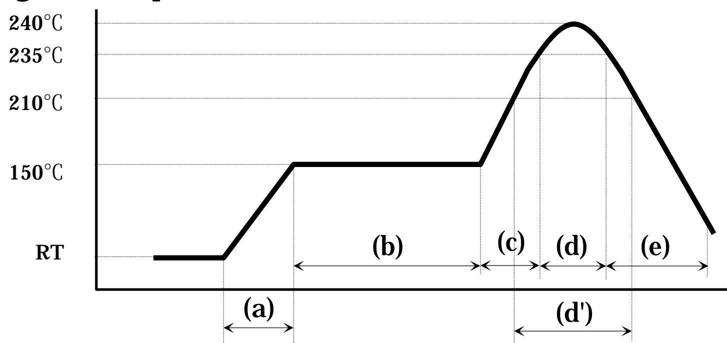
■ Recommended Mounting Method/Temp. Profiles for Symbol `R'.

Mounting Method	Conditions	Remarks
IR Reflow	Fig.1	Air convection is also the subjected method.
VPR	Fig.2	

IR Reflow : Infrared Reflow
VPR : Vapor Phase Reflow

* In the case of manual soldering, it is a partial heating method and the thermal stress will be applied only to the leads. Therefore, control of manufacturing conditions/floor life is not necessary.

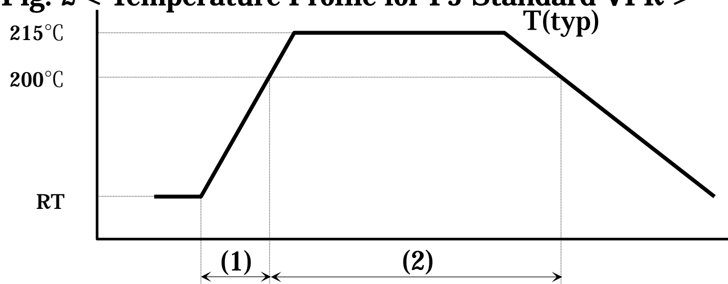
Fig. 1 < Temperature Profile for FJ Standard IR Reflow >



(a) Average ramp-up rate — 1℃/s to 4℃/s (average)
(b) Preheat temperature — 150℃to 190℃,60-120s
(c) Average ramp-up rate — 1℃/s to 4℃/s (average)
(d) Peak temperature range — Peak temp.= 240℃, Temp. maintained above 235℃=10s
(d') — Temp. maintained above 210℃= 40s(max.)
(e) Ramp-down rate — Natural cooling or forced cooling

Note) All temperatures refer to top surface of the package.

Fig. 2 < Temperature Profile for FJ Standard VPR >



(1) Average ramp-up rate — 1 to 8℃/s
(2) Peak temperature range — Temp. maintained above 200℃[T (typ) :215℃]=30s to 60s

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